



NEWS RELEASE

SiSoft to Lead Signal Integrity Boot Camp at DesignCon 2017

Santa Clara, CA – January 30, 2017 -- Signal Integrity Software Inc. announced that it will present a full-day signal integrity training session, "Pragmatic Signal Integrity", at DesignCon 2017 on Tuesday, January 31. DesignCon will be taking place at the Santa Clara Convention Center January 31-Feb 2, 2017.

The boot camp will be led by SiSoft's own 2015 DesignCon Engineer of the Year, Michael Steinberger, and will feature multiple presenters including signal integrity experts from SiSoft as well as Donald Telian from SiGuys.

A typical signal integrity project can involve a dozen or more models of several different types and involve at least three different analysis/simulation methods. Through interactive demonstration of the development of a typical SI project, this tutorial will offer attendees the disciplines needed to manage this complexity and consistently produce trustworthy results. This tutorial emphasizes the typical problems encountered, with each problem solved as a class exercise.

About SiSoft

SiSoft collaborates with customers and their suppliers to develop innovative solutions to the world's toughest high-speed design problems. SiSoft accelerates design cycles through a combination of award-winning EDA simulation software, methodology training and consulting services. Quantum Channel Designer (QCD) is the Industry's Premier Channel Simulator for the design and analysis of Multi-Gigabit serial links and a DesignVision Award Winner. Quantum-SI (QSI) is the leading solution for integrated signal integrity, timing and crosstalk analysis of high-speed parallel interfaces. SiSoft's products automate comprehensive pre- and post-route analysis of high speed interfaces, detailing a design's operating voltage and timing margins. More information on SiSoft can be found at www.sisoft.com.

About DesignCon

DesignCon is the world's premier conference for chip, board, and systems design engineers in the high-speed communications and semiconductor communities. DesignCon, created by engineers for engineers, takes place annually in Silicon Valley and remains the largest gathering of chip, board, and systems designers in the country. This three-day technical conference and expo combines technical paper sessions, tutorials, industry panels, product demos and exhibits from the industry's leading experts and solutions providers. More information is available at: designcon.com. DesignCon is organized by UBM Americas, a part of UBM plc (UBM.L), an

Events First marketing and communications services business. For more information, visit ubmamericas.com.

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